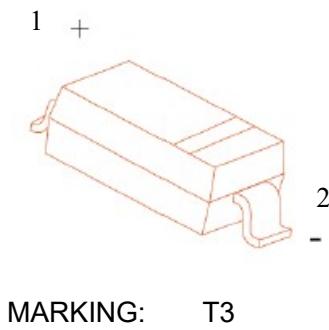


SOD-123

特征 Features

- 开关速度小于 50nS; Fast Switching Device (TRR <50nS)
- 最大功率耗散 500mW; Power Dissipation of 500mW
- 高稳定性和可靠性。High Stability and High Reliability
- 反向漏电流小。Low reverse leakage

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

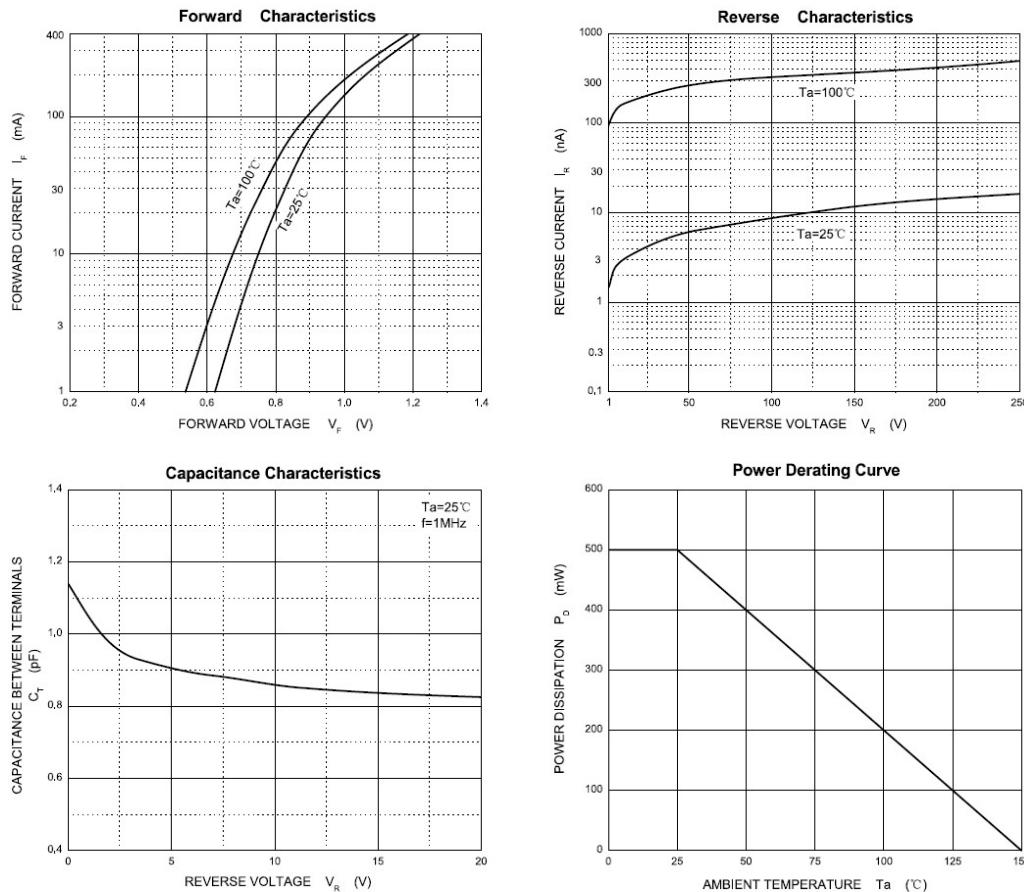
Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value		单位 Unit
		BAV21W-E3-08-CN		
反向电压 Reverse Voltage	VR	250		V
反向峰值电压 Peak Reverse Voltage	VRM	250		V
功率消耗 Power Dissipation	Pd	500		mW
工作结温 Operating junction temperature	Tj	150		°C
存储温度 Storage temperature range	Ts	-65~+150		°C
热阻 Thermal Resistance from Junction to Ambient	R _{θ JA}	250		°C/W
反向工作电压 Working Inverse Voltage	WIV	75		V
平均整流电流 Average Rectified Current	IO	200		mA
正向(不重复)电流 Non-repetitive Peak Forward Current	IFM	400		mA
正向(不重复)浪涌电流 Peak Forward Surge Current @tp=1ms; TA=25°C	IFSM	2.5		A

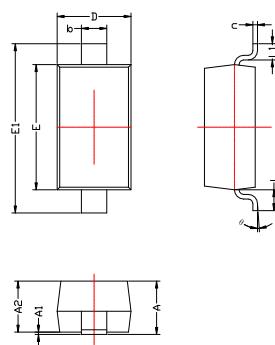
Valid provided that electrodes are kept at ambient temperature.

电特性 Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

符号 Symbols	参数 Parameter	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
VRB	反向击穿电压 Reverse Voltage	IB=100uA	250	---	V
IR	反向漏电电流	VR=200V	---	0.1	uA
	Reverse Leakage Current				
VF	正向电压 Forward Voltage	IF=100mA IF=200mA	---	1.00 1.25	V
	Forward Voltage	IF=200mA	---	1.25	
TRR	反向恢复时间 Reverse Recovery Time	IF= 30mA, IR=30mA RL=100Ω	---	50	nS
	Reverse Recovery Time	RL=100Ω			
		IRR=3mA			
C	结电容 Capacitance	VR=0V, f=1MHZ	---	5	pF
	Capacitance				

Typical Characteristics

SOD-123 PACKAGE OUTLINE

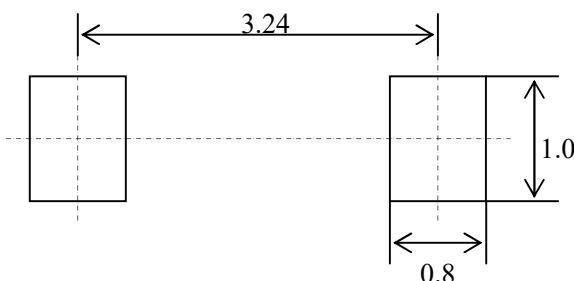
Plastic surface mounted package



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考 Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24

技术要求:

脚 宽: 0.55

1, 塑封体尺寸: 2.70 X 1.60

焊盘宽: 1.00

2: 未注公差为: ±0.05

脚 长: 0.50

3, 所有单位: mm

焊盘长: 0.80

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